In the Claims:

Please amend Claim 35 to read as follows:

35. (Once Amended) A method for simulating any wiring direction in an integrated circuit using wires deposed in diagonal and Manhattan directions, the method comprising the steps of:

providing at least one metal layer comprising at least two pairs of conductors to interconnect one or more points on the integrated circuit, wherein a conductor comprises one or more wires and a wire comprises a continuous segment deposed in a single direction;

for each pair of conductors:

deposing a first wire in a Manhattan direction relative to the boundaries of the integrated circuit, the first wire comprising a first wire length including first and second ends;

deposing a second wire in a diagonal direction relative to the boundaries of the integrated circuit, the second wire comprising a second wire length including first and second ends;

coupling the first end of the second wire to the second end of the first wire; and

wherein, an effective direction of the pairs of conductors comprises an angle, A, measured relative to the boundaries of the integrated circuit, defined by the expression Tan A = Y/X,

wherein, Y comprises a line segment with a distance starting from the second end of the second wire in the last conductor pair and ending at an intersection with a line segment propagated from the first end of the first wire and in the direction of the

first wire, and X comprises a distance, measured in the direction of the first wire, starting from the first end of the first wire and ending with the intersection of the Y line segment.